

ON Semiconductor				7/21/2020
Base Part		NCP3284	HF	
Orderable Part		NCP3284MNTXG	Total weight (mg)	86.363237
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Clip	6.800359	Zinc (Zn)	7440-66-6	0.11999367
		Iron (Fe)	7439-89-6	2.40000565
		Copper (Cu)	7440-50-8	97.40000491
		Phosphorus (P)	7723-14-0	0.07999578
Clip Attach	0.1	Titanium Dioxide (TiO2)	13463-67-7	7.5
		Proprietary	proprietary	6.5
		Bismaleimide	13676-54-5	28
		PTFE	9002-84-0	58
Die	2.762874	Silicon (Si)	7440-21-3	100
Die Attach Solder	4.401028	Silver (Ag)	7440-22-4	2.5
		Lead (Pb)	7439-92-1	92.5
		Tin (Sn)	7440-31-5	5
Lead Frame	32.999572	Silver (Ag)	7440-22-4	5
		Zinc (Zn)	7440-66-6	0.12
		Iron (Fe)	7439-89-6	2.4
		Copper (Cu)	7440-50-8	92.4
Mold Compound-Black	36.099511	Phosphorus (P)	7723-14-0	0.08
		Ortho Cresol Novolac Resin	29690-82-2	6.4999994
		Carbon Black (C)	1333-86-4	0.50000123
		Silica (SiO2)	14464-46-1	88.00000089
Plating	2.999832	Phenolic Resin (Novolac)	9003-35-4	4.99999848
Wire Bond - Cu	0.200061	Tin (Sn)	7440-31-5	100
		Palladium (Pd)	7440-05-3	1.8
		Gold (Au)	7440-57-5	0.1
		Copper (Cu)	7440-50-8	98.1
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of RoHS restricted substances. Lead (Pb) and lead oxide (PbO) are exempted with the RoHS exemption 7(a), 7(c) and 15. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>https://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				